

ET1847

End Termination

Description

ET1847 is a silver end termination designed for axial and radial lead attachment to MLCC (multilayer ceramic chip capacitors). ET1847 offers excellent solderability and adhesion. ET1847 is supplied at a rheology suitable for machine dip application.

Key Features

- Suitable rheology for machine dip application Excellent solderability



This picture does not show the packaging of ET1847 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

Viscosity	15 – 25 Kcps Brookfield RVT SC4 – 14 spindle, 6R utility cup at 10 rpm, 25 °C
Solids	81.5 ± 1.0 %
Alloy Ratio	100
Metal	Ag

Recommended Processing Guide

Drying Temperature	150 °C for 10 minutes
Process Temperature (TDS)	650 – 800 °C peak temperature Dwell time of 4 – 6 minutes at peak
Recommended Thinner	RV-372

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Warranty

6 months

Storage

Store in a dry location at 5 – 25 °C.

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